

Please add the following new claims:

--13. (New) A micropatterned thermosensor, comprising:

a supporting body; and

at least one thermocouple located on the supporting body, the thermocouple including a first material and a second material which form at least in a point-wise manner, at least one thermal contact with each other, at least one of the first material and the second material at least regionally configured in the form of one of a meander-shaped and an undulating-type circuit trace and arranged on the supporting body.

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Cont 14. (New) The micropatterned thermosensor according to claim 13, wherein the micropatterned thermosensor includes an infrared sensor.

15. (New) The micropatterned thermosensor according to claim 13, wherein the first material and the second material extend one of substantially side-by-side in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts, and extend over one another at least regionally in the form of circuit traces, the first material and the second material electrically insulated from one another with the exception of thermal contacts.

16. (New) The micropatterned thermosensor according to claim 15, wherein the thermocouple includes a plurality of thermal contacts configured as one of a thermal chain and a thermal column, at least two of the thermal contacts exposed to different temperatures.

17. (New) The micropatterned thermosensor according to claim 16, wherein a first one of the thermal contacts is exposed to a first temperature, the first temperature kept one of constant and at least approximately constant, and a second one of the thermal contacts is exposed to a second temperature, the second temperature to be one of detected and measured, the thermosensor further comprising an additional measuring device configured to detect the first temperature.

18. (New) The micropatterned thermosensor according to claim 17, wherein the measuring device one of includes a part of one of one of the circuit traces, arranged in the vicinity of one of the first thermal contact, and of a conductor and includes a reference circuit

trace as a sensitive component, arranged in a vicinity of the first thermal contact, and wherein the measuring device includes an evaluation arrangement configured to determine a temperature dependent, electrical resistance of one of the part of the trace, the conductor and the reference circuit trace.

19. (New) The micropatterned thermosensor according to claim 13, wherein at least one of the first and the second material includes a material having low thermal conductivity.

a 20. (New) The micropatterned thermosensor according to claim 13, wherein the first and the second material includes at least one of platinum, gold, lead tellurides, aluminum, titanium, polysilicon, doped polysilicon, polysilicon-germanium, and doped polysilicon-germanium.

21. (New) The micropatterned thermosensor according to claim 20, wherein the first material includes one of doped and undoped polysilicon-germanium and the second material includes platinum.

22. (New) The micropatterned thermosensor according to claim 18, wherein the one of the part of the circuit trace, the conductor and the reference circuit trace includes a platinum circuit trace.

23. (New) A micropatterned thermosensor, comprising:
a supporting body; and
at least one thermocouple located on the supporting body, the thermocouple including a first material and a second material, which form at least in a point-wise manner at least one thermal contact with each other, the second material including platinum and the first material including one of doped and undoped polysilicon-germanium.

24. (New) The micropatterned thermosensor according to claim 23, wherein the micropatterned thermosensor includes an infrared sensor.

25. (New) The micropatterned thermosensor according to claim 23, wherein at least one of the first material and the second material is configured at least regionally in a form of